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(54) **METHODS OF FORMING NANOSTRUCTURES USING SELF-ASSEMBLED NUCLEIC ACIDS, AND NANOSTRUCTURES THEROF**

(58) **Field of Classification Search**
CPC H01L 21/02118; H01L 21/02227; H01L 21/0332; H01L 21/0337; H01L 21/0338;
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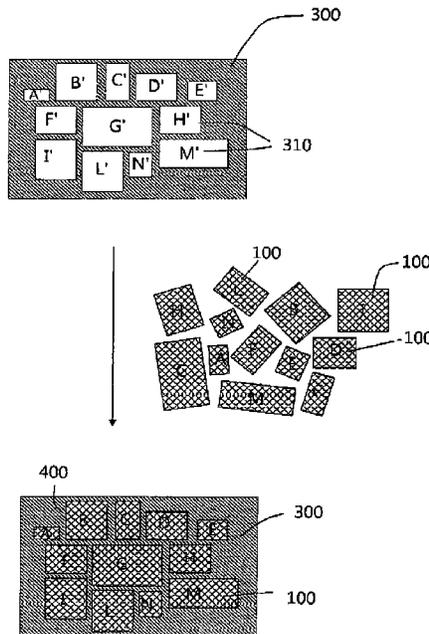
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(57) **ABSTRACT**

A method of forming a nanostructure comprises forming a directed self-assembly of nucleic acid structures on a patterned substrate. The patterned substrate comprises multiple regions. Each of the regions on the patterned substrate is specifically tailored for adsorption of specific nucleic acid structure in the directed self-assembly.

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H01L 29/02 (2006.01)
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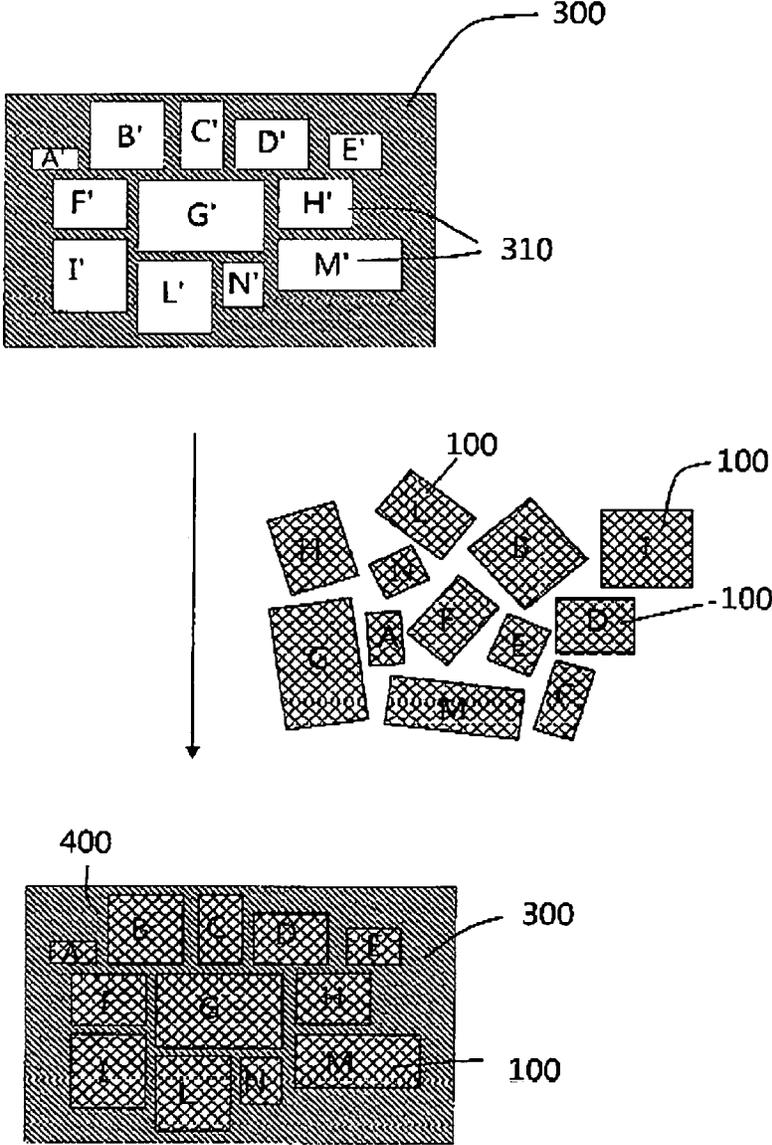


FIG. 1

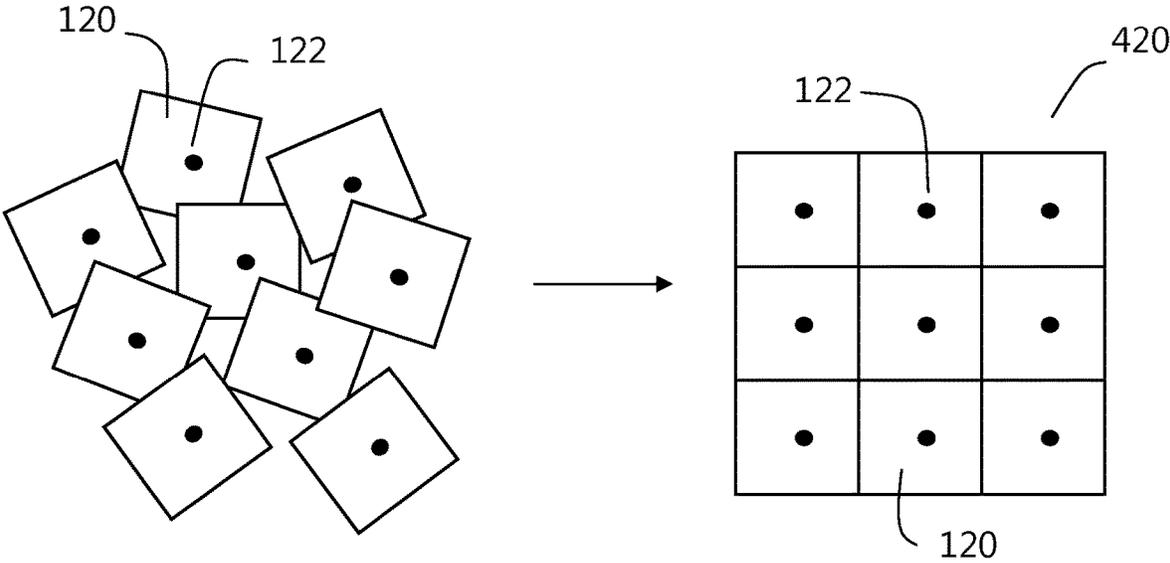


FIG. 2

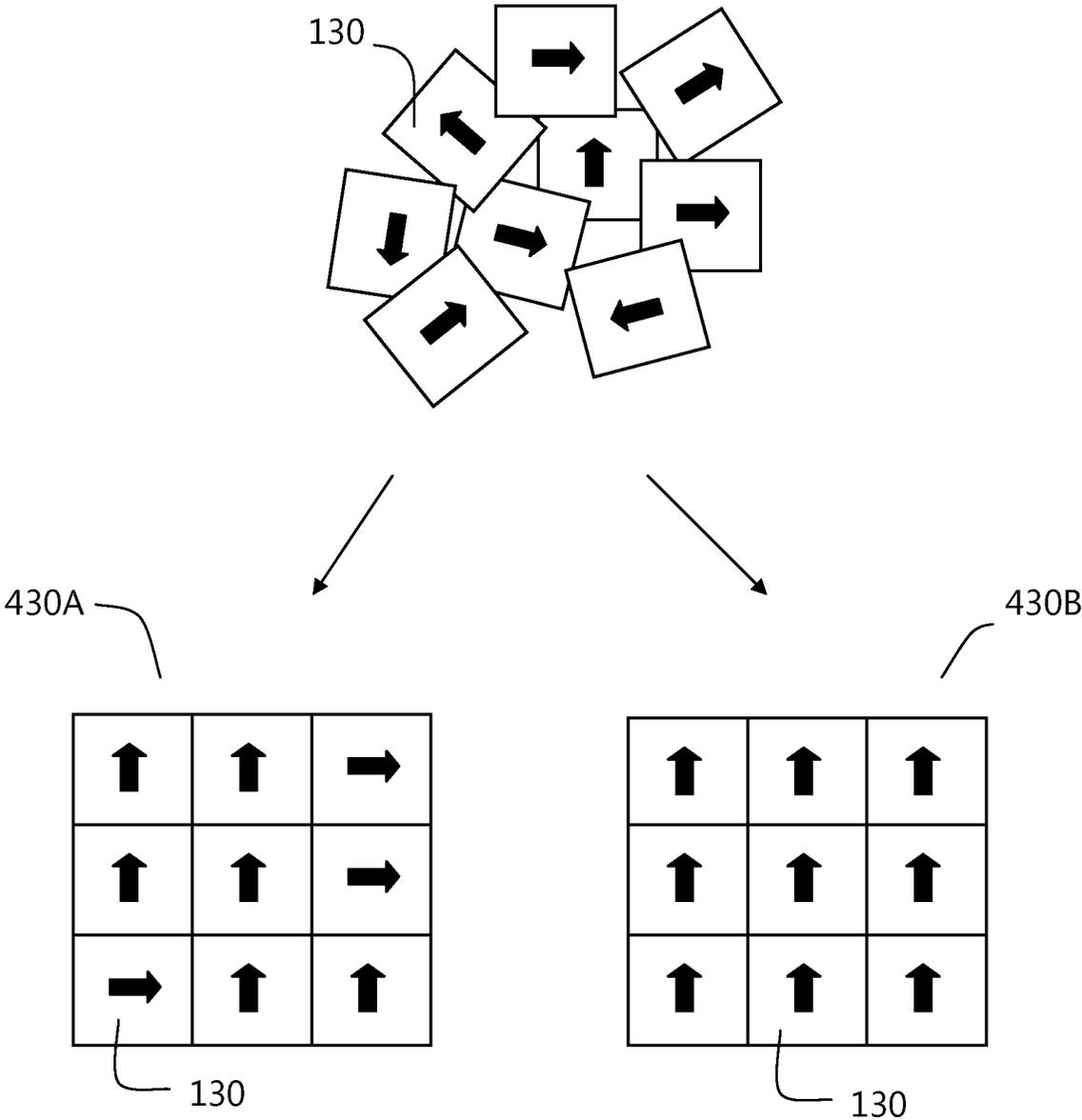


FIG. 3

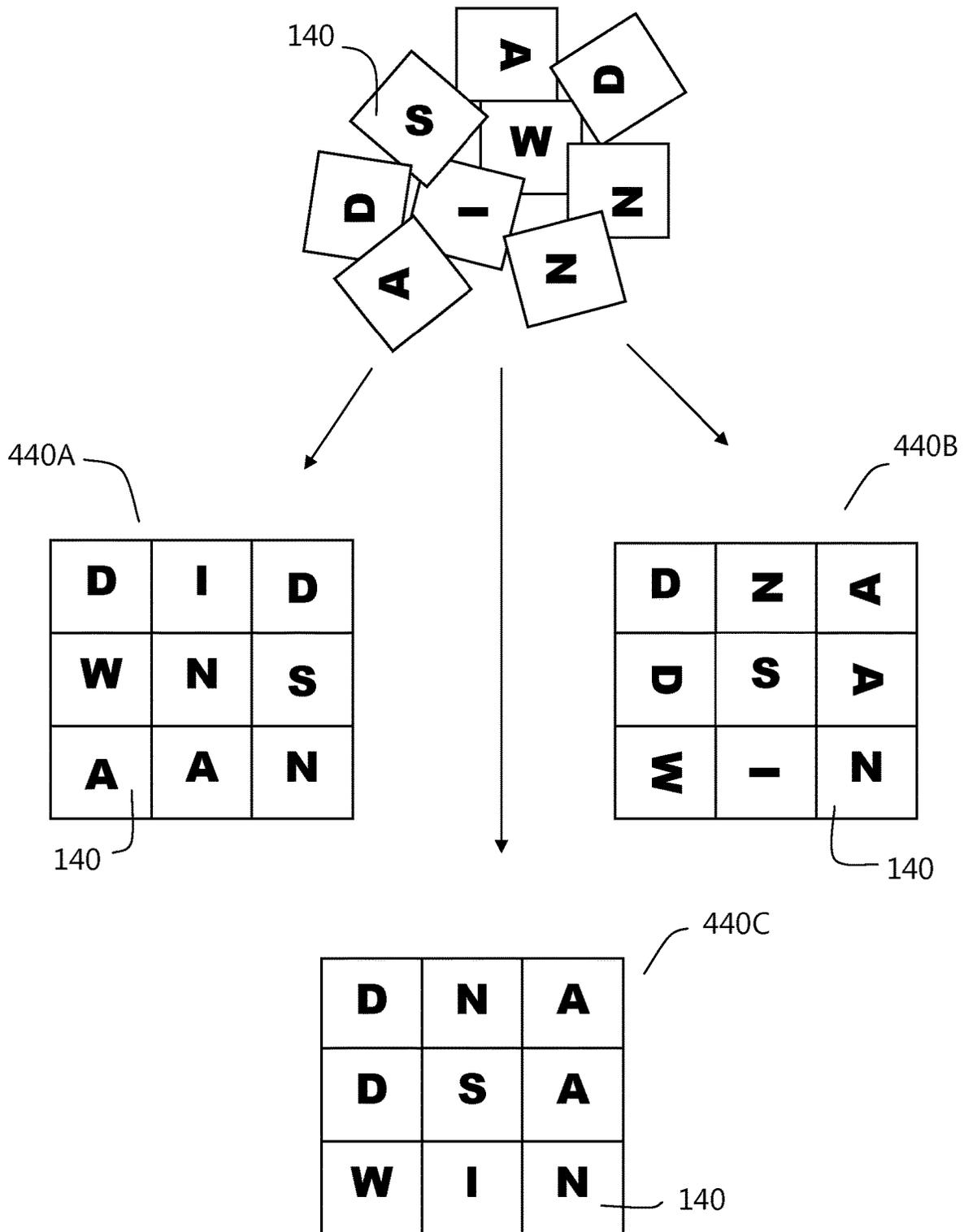


FIG. 4

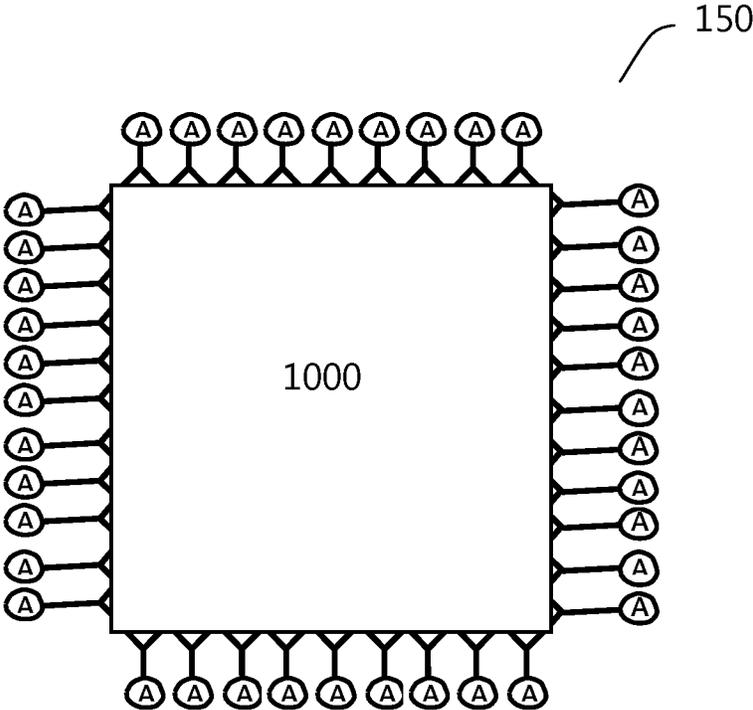


FIG. 5a

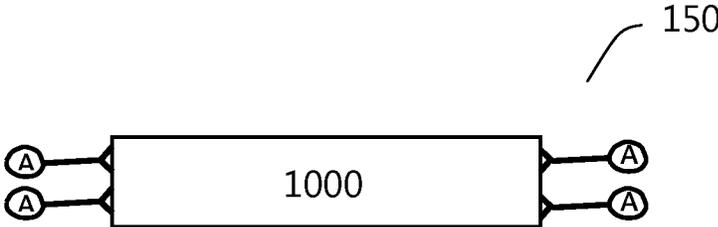


FIG. 5b

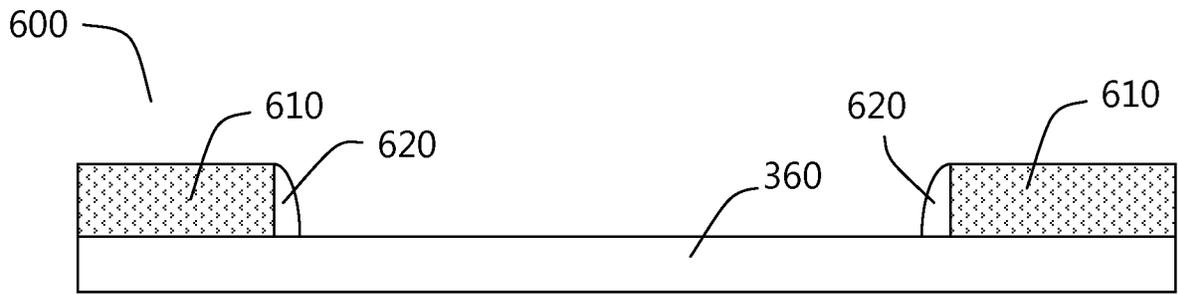


FIG. 6



FIG. 7

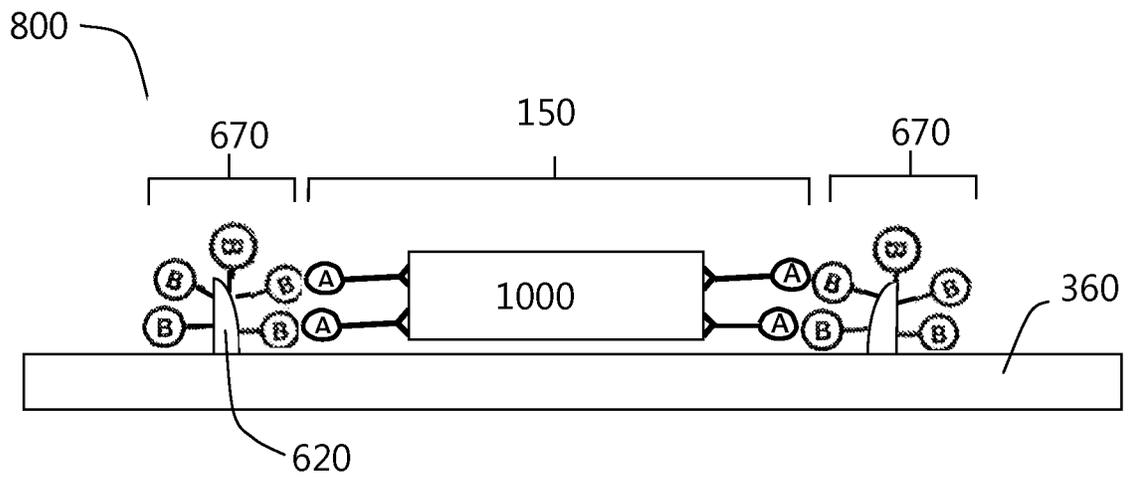


FIG. 8

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**METHODS OF FORMING
NANOSTRUCTURES USING
SELF-ASSEMBLED NUCLEIC ACIDS, AND
NANOSTRUCTURES THEREOF**

Matter enclosed in heavy brackets [] appears in the original patent but forms no part of this reissue specification; matter printed in italics indicates the additions made by reissue; a claim printed with strikethrough indicates that the claim was canceled, disclaimed, or held invalid by a prior post-patent action or proceeding.

Notice: This is a reissue application of U.S. Pat. No. 10,741,382, issued Aug. 11, 2020, to Sills et al. for METHODS OF FORMING NANOSTRUCTURES USING SELF-ASSEMBLED NUCLEIC ACIDS, AND NANOSTRUCTURES THEREOF. Because the present application is a reissue application, the amendments are made pursuant to 37 C.F.R. § 1.173 which requires the use of brackets and underlining.

CROSS-REFERENCE TO RELATED
APPLICATION

This application is a continuation of U.S. patent application Ser. No. 14/677,445, filed Apr. 2, 2015, now U.S. Pat. No. 9,881,786, issued Jan. 30, 2018, the disclosure of which is hereby incorporated herein in its entirety by this reference.

FIELD

The present disclosure, in various embodiments, relates generally to methods of forming nanostructures using self-assembly of nucleic acids.

BACKGROUND

A continuing goal of integrated circuit fabrication is to decrease the dimensions thereof. Integrated circuit dimensions can be decreased by reducing the dimensions and spacing of the constituent features or structures. For example, by decreasing the dimensions and spacing of semiconductor features (e.g., storage capacitors, access transistors, access lines) of a memory device, the overall dimensions of the memory device may be decreased while maintaining or increasing the storage capacity of the memory device.

As the dimensions and spacing of semiconductor device features become smaller, conventional lithographic processes for forming the semiconductor device features become increasingly more difficult and expensive to conduct. Therefore, significant challenges are encountered in the fabrication of nanostructures, particularly structures having a feature dimension (e.g., critical dimension) less than a resolution limit of conventional photolithography techniques (currently about 40 nm). It is possible to fabricate semiconductor structures with such feature dimensions using a costly pitch division or double patterning technologies. However, use of such processes is limited because the exposure tools are extremely expensive or extremely slow and, further, may not be amenable to formation of structures having dimensions of less than 20 nm.

The development of new processes, as well as materials useful in such processes, is of increasing importance to make the fabrication of small-scale devices easier, less expensive,

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and more versatile. One example of a method of fabricating small-scale devices that addresses some of the drawbacks of conventional lithographic techniques is directed self-assembly (DSA) of phase separated block copolymers.

Although DSA block copolymer is useful for fabrication of semiconductor structures having dimensions of less than 40 nm, the self-assembled block copolymer materials are generally restricted to periodic patterns and may not produce nanostructures exhibiting sufficiently low defect levels.

Self-assembled nucleic acids have been investigated for forming semiconductor devices. The specificity of complementary base pairing in nucleic acids provides self-assembled nucleic acids that may be used for self-assembled nucleic acid lithography processes.

U.S. Pat. No. 8,501,923 discloses a self-assembled DNA origami structure. The DNA origami structure is formed from structural units, wherein each structural unit comprises a single stranded polynucleotide scaffold and a plurality of helper/staple strands. The helper/staple strands are designed to be at least partially complementary to the single stranded polynucleotide scaffold such that the helper/staple strands self-anneal with the single stranded polynucleotide scaffold into a structural unit. The DNA origami structure may have dimensions of 100-200 nm with a resolution of 6 nm.

Arbitrary two-dimensional (2D) patterns of self-assembled nucleic acids have been reported in Wei et al., Complex shapes self-assembled from single stranded DNA tiles, *Nature*, 485 (2012), 623-627. The arbitrary 2D patterns are created using self-assembled DNA molecular canvases that are formed from DNA subunits. The DNA subunit has dimensions of less than 10 nm. The DNA subunit may be a single strand DNA having dimensions of 3 nm. The self-assembled DNA molecular canvas may have dimensions of 200 nm.

Surwade et al. disclose a method of forming custom-shaped inorganic oxide nanostructures by using self-assembled DNA-nanostructure templates. Surwade et al., Nanoscale Growth and Patterning of Inorganic Oxides Using DNA Nanostructure Templates," *J. Am. Chem. Soc.*, 135 (2013), 6778-6781. The self-assembled DNA nanostructure is deposited on a substrate without registration, and then used as a template for a selective deposition of inorganic oxide material to provide an inorganic oxide nanostructure. The inorganic oxide nanostructure may be used as a hard mask for etching the substrate.

Kershner et al. disclose the placement and orientation of individual self-assembled DNA structures on a lithographically patterned substrate. Kershner et al., Placement and orientation of individual DNA shapes on lithographically patterned surfaces, *Nature Nanotechnology*, 4 (2009), 557-561. DNA origami, in which a long single strand of DNA is folded into a shape using shorter "staple strands," is used as the self-assembled DNA structure. Electron beam lithography and dry oxidative etching are used to create DNA origami-shaped binding sites on the materials such as silicon dioxide (SiO₂) and diamond-like carbon (DLC).

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 shows top views of stages of forming a directed self-assembly of multiple DNA structures on a patterned substrate according to one embodiment of the present disclosure;

FIG. 2 shows a directed self-assembly of multiple isotropic DNA structures according to one embodiment of the present disclosure;

FIG. 3 shows a directed self-assembly of multiple anisotropic DNA structures according to one embodiment of the present disclosure;

FIG. 4 shows a directed self-assembly of multiple anisotropic DNA structures according to another embodiment of the present disclosure;

FIG. 5a is a top view of a functionalized DNA structure;

FIG. 5b is a cross-sectional view of a functionalized DNA structure;

FIG. 6 shows a semiconductor structure comprising a substrate, a sacrificial pattern material, and spacers;

FIG. 7 shows a patterned substrate comprising a substrate and functionalized spacers; and

FIG. 8 shows a semiconductor structure comprising a substrate, functionalized spacers, and a functionalized DNA structure.

DETAILED DESCRIPTION

The following description provides specific details, such as material types, material thicknesses, and processing conditions in order to provide a thorough description of embodiments of the disclosure. However, a person of ordinary skill in the art will understand that embodiments of the present disclosure may be practiced without employing these specific details. Indeed, the embodiments of the present disclosure may be practiced in conjunction with conventional fabrication techniques employed in the industry.

In addition, the description provided herein does not form a complete process flow for forming nanostructures. Only those process acts and structures necessary to understand the embodiments of the present disclosure are described in detail below. Additional acts to form the complete nanostructures may be performed by conventional fabrication techniques. Also the drawings accompanying the application are for illustrative purposes only, and are thus not necessarily drawn to scale. Elements common between figures may retain the same numerical designation. Furthermore, while the materials described and illustrated herein may be formed as layers, the materials are not limited thereto and may be formed in other three-dimensional configurations.

As used herein, the singular forms “a,” “an,” and “the” are intended to include the plural forms as well, unless the context clearly indicates otherwise.

As used herein, the term “substrate” means and includes a base material or construction upon which additional materials are formed. The substrate may be, for example, a semiconductor substrate, a base semiconductor material on a supporting structure, a metal electrode or a semiconductor substrate having one or more materials, structures or regions formed thereon. The substrate may be a conventional silicon substrate, or other bulk substrate comprising a layer of semiconductive material. As used herein, the term “bulk substrate” means and includes not only silicon wafers, but also silicon-on-insulator (SOI) substrates, such as silicon-on-sapphire (SOS) substrates and silicon-on-glass (SOG) substrates, epitaxial layers of silicon on a base semiconductor foundation, or other semiconductor or optoelectronic materials, such as silicon-germanium ($\text{Si}_{1-x}\text{Ge}_x$, where x is, for example, a mole fraction between 0.2 and 0.8), germanium (Ge), gallium arsenide (GaAs), gallium nitride (GaN), or indium phosphide (InP), among others. Furthermore, when reference is made to a “substrate” in the following description, previous process acts may have been conducted to form materials, regions, or junctions in the base semiconductor structure or foundation. In one embodiment, the

substrate is a silicon-containing material, such as a silicon substrate. The substrate may be doped or undoped.

As used herein, the term “nucleic acid” means and includes a polymeric form of nucleotides (e.g., polynucleotides and oligonucleotides) of any length that comprises purine and pyrimidine bases, or chemically or biochemically modified purine and pyrimidine bases. Nucleic acids may comprise single stranded sequences, double stranded sequences, or portions of both double stranded or single stranded sequences. As non-limiting examples, the nucleic acid may include ribonucleic acid (RNA), deoxyribonucleic acid (DNA), peptide nucleic acid (PNA), or combinations thereof. The backbone of the polynucleotide may comprise sugars and phosphate groups as may typically be found in RNA or DNA, or modified sugar and/or phosphate groups. Furthermore, the polynucleotide may comprise modified nucleotides, such as methylated nucleotides and nucleotide analogs.

Disclosed embodiments relate generally to nanostructures comprising directed self-assemblies of nucleic acid structures on a patterned substrate, and to methods of forming the nanostructures. In some embodiments, the nucleic acid structure may be DNA structure. Non-limiting examples of such DNA structure may include those described in Wei et al., supra, or the DNA origami structure disclosed in U.S. Pat. No. 8,501,923. The patterned substrate comprises multiple regions. Upon bringing the nucleic acid structures into contact with the patterned substrate, the nucleic acid structures adsorb onto specific regions of the patterned substrate as directed by interactions between the nucleic acid structures and the patterned substrate to provide directed self-assembly of nucleic acid structures on the patterned substrate.

Accordingly, a nanostructure comprises directed self-assembly of nucleic acid structures on a patterned substrate. The patterned substrate comprises regions, wherein each of the regions is configured to selectively adsorb one of the nucleic acid structures in the directed self-assembly.

As used herein, the term “directed self-assembly of multiple DNA structures” or “DSA of multiple DNA structures” refers to a self-assembly of multiple DNA structures on the patterned substrate that is directed by interactions between the DNA structures and the patterned substrate to enable the selective adsorption of specific DNA structures to specific regions of the patterned substrate.

As shown in FIG. 1, DNA structure **100** may have different configurations, e.g., DNA structures A, B, C, D, E, F, G, H, I, L, M, and N. In some embodiments, the DNA structures **100** may be those DNA structures described in Wei et al., supra, that are composed of DNA subunits having dimensions of less than 10 nm. In some embodiments, the DNA structures **100** may comprise the DNA origami disclosed in U.S. Pat. No. 8,501,923 that has dimensions of 100-200 nm.

As shown in FIG. 1, a patterned substrate **300** comprises patterned regions **310** of different configurations, e.g., patterned regions A', B', C', D', E', F', G', H', I', L', M', and N'. The patterned substrate **300** is prepared by selectively patterning a substrate to create multiple regions **310**, wherein each of the regions **310** is for a specific DNA structure. In some embodiments and as described in more detail below, the substrate is patterned to create regions that exhibit chemical specificity with the DNA structures. For example, the regions of the patterned substrate include chemical specificity for adsorbing the DNA structures, such as via Van der Waals, ionic and/or electrostatic interactions. In some embodiments, the substrate is patterned to create regions

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that have topological specificity with the DNA structures. For example, the regions of the patterned substrate have size and/or morphology corresponding to the size and/or morphology of the DNA structures. In some embodiments, the substrate is patterned to create regions that exhibit both chemical and topological specificity with the DNA structures. As shown in FIG. 1, the region A' of the patterned substrate **300** corresponds in size and/or morphology to the size and/or morphology of the DNA structure A, and the region B' corresponds in size and/or morphology to the size and/or morphology of DNA structure B. Any conventional techniques may be used to pattern the substrate.

Accordingly, a method of forming a nanostructure comprises forming a directed self-assembly of nucleic acid structures on a patterned substrate. The patterned substrate comprises multiple regions. Each of the regions on the patterned substrate is specifically tailored for adsorption of a specific nucleic acid structure in the directed self-assembly of nucleic acid structures.

In FIG. 2, a directed self-assembly **420** is formed from nine DNA structures **120** on a patterned substrate (not shown). As shown in FIG. 2, each of the DNA structures **120** has the same configuration, such as the same length and width with an opening **122** in the middle of the DNA structure **120**. The dimensions of the opening **122** are at a sublithographic scale. As with the embodiment described for FIG. 1, the patterned substrate may include regions that correspond in size and/or morphology to the size and/or morphology of the DNA structures **120**. The DNA structure **120** is isotropic (i.e., the DNA structure has physical properties that are the same regardless of the direction of measurement). Since the DNA structures **120** are isotropic, the DSA **420** of DNA structures **120** is not susceptible to orientational or sequential placement errors. Thus, each of the nine DNA structures **120** may adsorb to any region of the patterned substrate and neither orientational control nor sequential control is required for the formation of DSA **420**. Furthermore, the patterned substrate may include regions that correspond in size and/or shape of the array of the DNA structures **120**.

By way of non-limiting example, in some embodiments, the nine isotropic DNA structures **120** may form a 3x3 array-DSA on the patterned substrate. Since each of the DNA structures **120** includes the opening **122**, the DSA **420** of DNA structures **120** may be used to create a contact hole pattern in a semiconductor device, with the holes having sublithographic dimensions. In some other embodiments, each of the DNA structures **120** includes plurality of openings at a sublithographic pitch. The DSA **420** of DNA structures **120** enables a large array of sublithographic features or pillars at a sublithographic pitch.

In FIG. 3, a directed self-assembly is formed from nine anisotropic DNA structures **130** assembled into a 3x3 array on a patterned substrate (not shown). The arrow symbol on the DNA structures **130** indicates the required orientation of the structure containing the sublithographic pattern. As with the embodiment described for FIG. 1, the patterned substrate may include regions that correspond in size and/or morphology to the size and/or morphology of the DNA structures **130**. The DNA structure **130** is anisotropic (i.e., the DNA structure has physical properties that differ based on the direction of measurement). Since the DNA structures **130** are anisotropic, the DSA of DNA structures **130** does not always provide a desired DSA unless orientational control is provided during the adsorption of the anisotropic DNA structures **130** to the patterned substrate. Without providing orientational control, the anisotropic DNA structures **130**

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may assemble into undesirable DSA **430A**, where the arrows pointing in different directions indicate orientation errors. With orientational control, the anisotropic DNA structures **130** may assemble into the desired DSA **430B**, where the arrows pointing in same directions indicate the absence of orientation errors. By way of non-limited example, the nine anisotropic DNA structures **130** may form a 3x3 array-DSA on the patterned substrate. The DSA **430B** may be used to create a sublithographic logic gate or interconnect patterns in semiconductor devices where sequence is not critical.

In FIG. 4, a directed self-assembly is formed from nine anisotropic DNA structures **140** assembled into a 3x3 array on a patterned substrate (not shown). The letter symbols on the DNA structures **140** indicate that the sublithographic features to be transferred to the substrate require specific orientation and sequence control. The sublithographic features may include regular, periodic, patterns or irregular, i.e., sparse, patterns, corresponding to dense array features or peripheral routing, logic, interconnects, or contacts. As with the embodiment described for FIG. 1, the patterned substrate may include regions that correspond in size and/or morphology to the size and/or morphology of the DNA structures **140**. Since the DNA structures **140** are anisotropic, the DSA of DNA structures **140** does not always provide a desired DSA unless orientational and sequential control is provided. If orientational control is provided but no sequential control is provided, the anisotropic DNA structures **140** may assemble into undesirable DSA **440A**. As shown, although all letters in the DSA **440A** are in the desired upright orientation, the DSA **440A** does not provide any discernible message. If sequential control is provided but no orientational control is provided, the anisotropic DNA structures **140** may assemble into undesirable DSA **440B**. As shown, all letters in the DSA **440B** are in the desired sequence. However, the DSA **440B** does not provide any discernible message because some letters are not in the desirable upright orientation. When both orientational control and sequential control are provided, the anisotropic DNA structures **140** may assemble into the desired DSA **440C** so that the message (e.g., "DNA DSA WIN") may be read. Thus, in the embodiment as shown in FIG. 4, both orientational control and sequential control are provided during assembling of DNA structures **140** to provide the directed self-assembly **440C** of multiple DNA structures with minimum orientational and sequential errors.

Accordingly, a nanostructure comprises directed self-assembly of DNA structures on a patterned substrate. The patterned substrate comprises regions, wherein each of the regions is configured to selectively adsorb a specific DNA structure in the directed self-assembly of DNA structures.

In some embodiments, the directed self-assembly of DNA structures is formed on the patterned substrate with an orientational control. In some embodiments, the directed self-assembly of DNA structures is formed on the patterned substrate with a sequential control. In some embodiments, the directed self-assembly of DNA structures is formed on the patterned substrate with both orientational and sequential controls.

Each of the regions on the patterned substrate corresponds to a DNA structure in the DSA of multiple DNA structures. The selective adsorption of the specific DNA structure to the specific region on the patterned substrate is driven thermodynamically by an energy minimization of the resulting DSA of the multiple DNA structures. As described in more detail below, a specific DNA structure may adsorb to its corresponding region on the patterned substrate by achieving its lowest energy configuration. Adsorption between a

specific DNA structure and its corresponding region of the patterned substrate may be energetically favorable, while adsorption between a specific DNA structure and other regions of the patterned substrate may be energetically unfavorable.

In some embodiments and as described in more detail below, the regions of the patterned substrate include chemical specificity for adsorbing to the DNA structures, such as via Van der Waals, ionic, and/or electrostatic interactions. In some embodiments, the regions of the patterned substrate include topological specificity to the DNA structures. In some embodiments, the regions of the patterned substrate include both topological and chemical specificity to the DNA structures.

FIGS. 5a, 5b, and 6-8 show various stages in the preparation of nanostructures according to some embodiments of the present disclosure.

FIGS. 5a and 5b show a top view and cross-sectional view, respectively, of a functionalized DNA structure 150. As shown, the functionalized DNA structure 150 comprises a DNA structure 1000 and multiple functional groups "A" on the DNA structure 1000. The functional groups "A" may include, but are not limited to, a phosphate linkage, a complementary RNA strand, a short DNA strand, or other reactive group. The DNA structure 1000 may include any of DNA structures 100, DNA structures 120, DNA structures 130, or DNA structures 140 as described above.

FIG. 6 shows a semiconductor structure 600 comprising a substrate 360, a sacrificial pattern material 610 on the substrate 360, and spacers 620. The sacrificial pattern material 610 and the spacers 620 may be formed on the substrate 360 by any conventional methods.

After removal of the sacrificial pattern material 610 from the semiconductor structure 600, the spacers 620 on the substrate 360 may be derivatized to include functional groups "B." The functional groups "B" have chemical specificity to the functional groups "A" of the functionalized DNA structure 150 shown in FIG. 5a or FIG. 5b.

As shown in FIG. 7, the patterned substrate 700 comprises the substrate 360 and functionalized spacers 670 protruding from the substrate 360. Each of the functionalized spacers 670 comprises a spacer 620 and multiple functional groups "B" on the spacer 620.

Upon contacting the functionalized DNA structure 150 with the patterned substrate 700, the chemical specificity between the functional groups "A" of the functionalized DNA structure 150 and the functional groups "B" on the functionalized spacers 670 of the patterned substrate 700 directs the selective absorption of the functionalized DNA structure 150 onto the specific region on the patterned substrate 700 to provide a semiconductor structure 800, as shown in FIG. 8. Favorable interactions between the "A" and "B" functional groups may enable the functionalized DNA structure 150 to selectively adsorb onto the specific region on the patterned substrate 700.

Accordingly, a method of forming a nanostructure comprises patterning a substrate to create a patterned substrate and contacting the patterned substrate with DNA structures. The patterned substrate comprises regions. The method further comprises selectively adsorbing the DNA structures to a specific region on the patterned substrate to form a self-assembly of DNA structures on the patterned substrate.

The nanostructures of present disclosure may be used for fabrication of various semiconductor structures and devices. By way of non-limiting example, the nanostructures, such as DSA 400, the DSA 420, the DSA 430B, or the DSA 440C described in FIGS. 1-4, may be used to transfer the sub-

lithographic features of the DNA structures 100, the DNA structures 120, the DNA structures 130, or the DNA structures 140 into the substrate, such as for fabricating sublithographic feature devices, contacts, contact holes, interconnects, etc. In some embodiments, the DSA of DNA structures may be removed during further processing acts of the fabrication of semiconductor structures and devices. In some embodiments, the DSA of DNA structures may remain during further processing acts of the fabrication.

The disclosed methods of forming nanostructures use the directed self-assembly of multiple DNA structures, and may provide the nanostructures having dimensions of less than 40 nm with reduced defect levels. Furthermore, the nanostructures may have any arbitrary structures depending on the designs of the DNA structures.

It is also understood that the directed self-assembly of DNA structures are used herein to exemplify the invention. The directed self-assembly of other nucleic acid structures may be used in the present disclosure, e.g., the directed self-assembly of RNA structures, the directed self-assembly of PNA structures, etc.

While the present disclosure is susceptible to various modifications and alternative forms, specific embodiments have been shown by way of example in the drawings and have been described in detail herein. However, the present disclosure is not intended to be limited to the particular forms disclosed. Rather, the present disclosure is to cover all modifications, equivalents, and alternatives falling within the scope of the present disclosure as defined by the following appended claims and their legal equivalents.

What is claimed is:

1. A method of forming a nanostructure, the method comprising:
 - forming a patterned semiconductive substrate comprising one or more regions, each of the one or more regions comprising one or more spacers, and each of the one or more spacers comprising functional groups tailored to adsorb a specific nucleic acid structure;
 - contacting the patterned semiconductive substrate with nucleic acid structures comprising the specific nucleic acid structures; and
 - selectively adsorbing the specific nucleic acid structures to the respective one or more regions of the patterned semiconductive substrate to form a directed self-assembly of nucleic acid structures on the patterned semiconductive substrate.
2. The method of claim 1, wherein forming a patterned semiconductive substrate comprises patterning the semiconductive substrate to create the one or more regions formulated to exhibit chemical specificity to the specific nucleic acid structures.
3. The method of claim 1, wherein forming a patterned semiconductive substrate comprises patterning the semiconductive substrate to create the one or more regions configured to exhibit topological specificity to the specific nucleic acid structures.
4. The method of claim 1, wherein forming a patterned semiconductive substrate comprising one or more regions comprises patterning the semiconductive substrate to comprise regions corresponding in at least one of size or morphology to at least one of size or morphology of the specific nucleic acid structures.
5. The method of claim 1, wherein selectively adsorbing the specific nucleic acid structures to the respective one or more regions of the patterned semiconductive substrate comprises achieving a lowest energy configuration between

adsorption of the specific nucleic acid structures to the one or more regions of the patterned semiconductor substrate.

6. The method of claim 1, wherein forming a directed self-assembly of nucleic acid structures on the patterned semiconductor substrate comprises forming the directed self-assembly comprising sublithographic openings in the nucleic acid structures.

7. The method of claim 1, wherein forming a directed self-assembly of nucleic acid structures on the patterned semiconductor substrate comprises forming the directed self-assembly comprising isotropic nucleic acid structures.

8. The method of claim 1, wherein forming a directed self-assembly of nucleic acid structures on the patterned semiconductor substrate comprises forming the directed self-assembly comprising sublithographic features at a sublithographic pitch on the patterned semiconductor substrate.

9. The method of claim 8, further comprising transferring the sublithographic features to the patterned semiconductor substrate.

10. The method of claim 1, wherein forming a directed self-assembly of nucleic acid structures on the patterned semiconductor substrate comprises forming the directed self-assembly comprising anisotropic nucleic acid structures.

11. The method of claim 10, wherein forming the directed self-assembly comprising anisotropic nucleic acid structures comprises providing orientational control and sequential control during the adsorption of the anisotropic nucleic acid structures to the patterned semiconductor substrate.

12. The method of claim 11, wherein providing orientational control and sequential control during the adsorption of the anisotropic nucleic acid structures comprises forming the directed self-assembly of nucleic acid structures with minimum orientational and sequential errors.

13. The method of claim 1, further comprising using the directed self-assembly of nucleic acid structures as a mask.

14. The method of claim 1, wherein selectively adsorbing the specific nucleic acid structures to the respective one or more regions of the patterned semiconductor substrate comprises selectively adsorbing specific deoxyribonucleic acid structures to the respective one or more regions.

15. The method of claim 1, wherein selectively adsorbing the specific nucleic acid structures to the respective one or more regions of the patterned semiconductor substrate comprises selectively adsorbing specific ribonucleic acid structures to the respective one or more regions.

16. The method of claim 1, wherein selectively adsorbing the specific nucleic acid structures to the respective one or more regions of the patterned semiconductor substrate comprises chemically interacting the specific nucleic acid structures with the respective one or more regions.

17. A method of forming a nanostructure, the method comprising:

[forming a patterned semiconductor substrate comprising at least one region tailored to adsorb a specific nucleic acid structure, the specific nucleic acid structure formulated to exhibit at least one of topological specificity or chemical specificity to the at least one region;]

contacting [the] a patterned semiconductor substrate with nucleic acid structures comprising [the] a specific nucleic acid structure, the patterned semiconductor substrate comprising at least one region, the at least one region comprising one or more spacers, each of the one or more spacers comprising functional groups tailored to adsorb the specific nucleic acid structure,

and the specific nucleic acid structure formulated to exhibit at least one of topological specificity or chemical specificity to the at least one region;

adsorbing the specific nucleic acid structure to the at least one region of the patterned semiconductor substrate to form a directed self-assembly of nucleic acid structures comprising sublithographic features on the patterned semiconductor substrate; and

transferring the sublithographic features to the patterned semiconductor substrate.

18. The method of claim 17, further comprising removing the directed self-assembly of nucleic acid structures.

19. A nanostructure comprising:

a directed self-assembly of nucleic acid structures on a patterned semiconductor substrate, the patterned semiconductor substrate comprising regions and a specific nucleic acid structure of the directed self-assembly of nucleic acid structures selectively adsorbed to each of the regions of the patterned semiconductor substrate, each of the regions corresponding in at least one of size or morphology to at least one of size or morphology of the specific nucleic acid structure, and each of the regions comprising one or more spacers, each of the one or more spacers comprising functional groups.

20. A nanostructure comprising:

a directed self-assembly of nucleic acid structures on a patterned semiconductor substrate, the patterned semiconductor substrate comprising regions and a specific nucleic acid structure of the directed self-assembly of nucleic acid structures selectively adsorbed to each of the regions of the patterned semiconductor substrate, each of the regions comprising one or more spacers, and each of the one or more spacers comprising functional groups formulated to exhibit chemical specificity to the specific nucleic acid structure.

21. The method of claim 1, wherein forming a patterned semiconductor substrate comprising one or more regions comprises forming the patterned semiconductor substrate comprising regions, each of the regions tailored to adsorb the same specific nucleic acid structure.

22. The method of claim 1, wherein forming a patterned semiconductor substrate comprising one or more regions comprises forming the patterned semiconductor substrate comprising regions, each of the regions tailored to adsorb a different specific nucleic acid structure.

23. The method of claim 17, wherein adsorbing the specific nucleic acid structure to the at least one region of the patterned semiconductor substrate comprises adsorbing the specific nucleic acid structure to the at least one region by chemical specificity.

24. The method of claim 17, wherein adsorbing the specific nucleic acid structure to the at least one region of the patterned semiconductor substrate comprises adsorbing the specific nucleic acid structure to the at least one region by topological specificity.

25. A method of forming a nanostructure, the method comprising:

providing a patterned semiconductor substrate comprising one or more regions, each of the one or more regions comprising one or more spacers, each of the one or more spacers comprising functional groups tailored to adsorb a specific nucleic acid structure; contacting the patterned semiconductor substrate with nucleic acid structures comprising the specific nucleic acid structures; and

selectively adsorbing the specific nucleic acid structures to the respective one or more regions of the patterned

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semiconductive substrate to form a directed self-assembly of nucleic acid structures on the patterned semiconductive substrate.

26. *A method of forming a nanostructure, the method comprising:*

5 *contacting a patterned semiconductive substrate with nucleic acid structures comprising specific nucleic acid structures, the patterned semiconductive substrate comprising one or more regions, each of the one or more regions comprising one or more spacers, each of the one or more spacers comprising functional groups tailored to adsorb a specific nucleic acid structure of the specific nucleic acid structures; and*

10 *adsorbing the specific nucleic acid structure to each of the one or more regions of the patterned semiconductive substrate to form a directed self-assembly of nucleic acid structures on the patterned semiconductive substrate.*

27. *A method of forming an assembly, the method comprising:*

15 *forming a patterned semiconductive substrate comprising regions, each of the regions comprising one or more spacers, each of the one or more spacers comprising functional groups tailored to couple with specific nucleic acid structures;*

20 *contacting the patterned semiconductive substrate with a mixture comprising the specific nucleic acid structures; and*

25 *coupling at least some of the specific nucleic acid structures to at least some of the regions to assemble a pattern of the specific nucleic acid structures on the patterned semiconductive substrate.*

28. *A method of forming an assembly, the method comprising:*

30 *forming a patterned semiconductive substrate comprising regions, each of the regions comprising one or more spacers, each of the one or more spacers comprising functional groups tailored to receive and retain specific nucleic acid structures;*

35 *contacting the patterned semiconductive substrate with a mixture comprising the specific nucleic acid structures; and*

40 *retaining at least some of the specific nucleic acid structures to at least some of the regions to assemble a distribution of the specific nucleic acid structures on the patterned semiconductive substrate.*

29. *A method of forming an assembly, the method comprising:*

45 *forming a patterned silicon-containing substrate comprising regions, each of the regions comprising one or more spacers, each of the one or more spacers comprising functional groups tailored to receive and retain nucleotide-containing structures;*

50 *contacting the patterned substrate with a mixture comprising the nucleotide-containing structures; and*
retaining at least some of the nucleotide-containing structures to at least some of the regions to form a distribution of the nucleotide-containing structures on the substrate.

30. *A method of forming a nanostructure, the method comprising:*

55 *contacting (a) a patterned semiconductive substrate comprising one or more regions with (b) nucleic acid structures,*

60 *each region of the one or more regions comprising one or more spacers, each of the one or more spacers com-*

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prising functional groups configured to chemically interact with functional groups on the nucleic acid structures,

65 *each nucleic acid structure of the nucleic acid structures comprising (i) a functional group and (ii) a specific nucleic acid structure capable of being adsorbed to the one or more regions of the patterned semiconductive substrate,*

70 *to allow selective adsorption of the specific nucleic acid structures to the respective one or more regions of the patterned semiconductive substrate, thereby forming the nanostructure.*

31. *The method of claim 30, wherein the nanostructure comprises a directed self-assembly of nucleic acid structures on the patterned semiconductive substrate.*

32. *A method of forming a nanostructure, the method comprising:*

75 *contacting a patterned semiconductive substrate with nucleic acid structures, the patterned semiconductive substrate comprising one or more regions, each of the one or more regions comprising one or more spacers, each of the one or more spacers comprising functional groups tailored to adsorb one or more nucleic acid structures,*

80 *each nucleic acid structure comprising (i) a functional group and (ii) a specific nucleic acid structure capable of being adsorbed to the one or more regions of the patterned semiconductive substrate,*

85 *to allow selective adsorption of the specific nucleic acid structures to the respective one or more regions of the patterned semiconductive substrate, thereby forming the nanostructure,*

90 *wherein the nanostructure comprises a directed self-assembly of nucleic acid structures on the patterned semiconductive substrate.*

33. *The method of claim 1, wherein each nucleic acid structure further comprises a functional group.*

34. *The method of claim 17, wherein each nucleic acid structure further comprises a functional group.*

35. *The nanostructure of claim 19, wherein each nucleic acid structure further comprises a functional group.*

36. *The nanostructure of claim 20, wherein each nucleic acid structure further comprises a functional group.*

37. *A method of forming a nanostructure, the method comprising:*

95 *contacting (a) a patterned semiconductive substrate comprising one or more regions with (b) nucleic acid structures,*

100 *each region of the one or more regions comprising one or more spacers, each of the one or more spacers comprising functional groups configured to chemically interact with the nucleic acid structures,*

105 *each nucleic acid structure comprising (i) a functional group and (ii) a specific nucleic acid structure formulated to be adsorbed to the one or more regions of the patterned semiconductive substrate,*

110 *to allow selective adsorption of the specific nucleic acid structures to the respective one or more regions of the patterned semiconductive substrate to form the nanostructure.*

38. *A method of forming a nanostructure, the method comprising:*

115 *contacting a patterned semiconductive substrate with nucleic acid structures, the patterned semiconductive substrate comprising one or more regions, each of the one or more regions comprising one or more spacers,*

each of the one or more spacers comprising functional groups tailored to adsorb nucleic acid structures, each nucleic acid structure comprising (i) a functional group and (ii) a specific nucleic acid structure formulated to be adsorbed to the one or more regions of the patterned semiconductive substrate, 5
to allow selective adsorption of the specific nucleic acid structures to the respective one or more regions of the patterned semiconductive substrate to form the nano- 10
structure,
wherein the nanostructure comprises a directed self-assembly of nucleic acid structures on the patterned semiconductive substrate.

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